Final Product Change Notification 201409009F01

Issue Date: 25-Sep-2014
Effective Date: 01-Feb-2015

Here’s your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Management Summary

Die re-layout to improve manufacturability for small footprint leadless packages

Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[X] Assembly Process
[ ] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

Improve manufacturability for small footprint leadless packages type 74AUP1T34

Details of this Change

Removal of bond-pads for leaded packages, replace existing die with new die in leadless packages

- Layout changes only, no product IP changes

Why do we Implement this Change

- Improve manufacturability and optimize processing robustness for new smaller footprint leadless packages

Identification of Affected Products

- The changed products can be identified by backward traceability of their marking date code

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 01-Feb-2015

Impact

No impact to the product's functionality anticipated

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 25-Oct-2014.

Remarks

- No change to form, fit or function anticipated
- No influence on quality or reliability anticipated
- No change to datasheet anticipated
- No change in ordering part number
- No change in product top side marking
- Layout changes only no product IP design changes

Additional information, see attached qualification report

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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